DATA-2017: IEEE INTERNATIONAL WORKSHOP on DEFECTS, ADAPTIVE TEST, YIELD AND DATA ANALYSIS

Will be held in conjunction with ITC 2017, on Nov. 2-3, 2017, In Fort Worth, TX

FORT WORTH

CALL FOR PAPERS AND PARTICIPATION
THEME: "Data in the Product Lifecycle"

In test, we use data every day. Yield data, throughput data, statistical data, reliability data, outlier data, general production data are all in everyday use. However, data means much more than that. Advances in our industry allow data from wafer fab to be reused in studying system level test results. Field failure studies now routinely uses wafer probe data to understand root cause. Data has now become a product life cycle requirement—cradle to grave. Today access to the data has become an issue; the control and sharing of data among business partners. How to efficiently process data to extract the golden nuggets of useful information amid the gigabytes of unimportant noise remains a focus and a challenge for test professionals.

The Organizing Committee for the DATA-2017 Workshop is soliciting papers in: semiconductor test, yield analysis, product learning, and quality improvement. Of particular interest are advanced techniques and new tools for the use of data during the entire product life cycle, with special attention to how data can be used to change and alter test flows and decisions (adaptive test). Preference will be given to real-world case studies.

Ideas or proposals for Embedded Tutorials, Debates, Panel Discussions and Poster style "Spot-Light" presentations describing industrial experiences or research are also invited.

Suggested Topics

- Real Time Analysis Methods
- Real Time Test Process Monitoring
- Yield Learning and Analysis
- Analog Fault Modeling and Coverage
- Analog Effects in Digital Logic
- Embedded Instrumentation (iJTAG)
- Advanced DPPM Reduction & Reliability Improvement Techniques
- Data Acquisition & Transport
- Adaptive Test for Product Engineers
- Data Analysis Methods, Including Multivariate Data
- Fault Localization and Diagnosis
- Data Storage and Security
- I/O Test, Tuning, and Adjustment
- Product and Project Case studies

To present at the workshop, send to smith.wesley@siemens.com a PDF version of an extended abstract or a full paper (Max 10 pages, double column, 11pt font size, IEEE proceeding format) by **September 20, 2017**. Each submission should include full name and address of each author, affiliation, telephone number, and Email address. Camera-ready papers for inclusion in the digest of papers will be due on **October 16, 2017**.

AUTHOR'S SCHEDULE Web-site at: http://DATA.tttc-events.org/

Submission Date:	**September 20, 2017**
Notification of Acceptance:	**October 2, 2017**
Camera Ready Paper (.pdf):	**October 16, 2017**
Final Presentation Slides (.ppt):	**October 23, 2017**

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